

RESPONSE TO OFFICE ACTION

Serial No. 10/616,097

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sun, et al.

Serial No.: 10/616,097

Examiner: Edna Wong

Confirmation No.: 1645

Title: MULTIPLE-STEP
ELECTRODEPOSITION PROCESS
FOR DIRECT COPPER PLATING ON
BARRIER MATERIALS

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Case: AMAT/8241/CMP/ECP/RKK

Filed: July 8, 2003

Group Art Unit: 1753

MAIL STOP Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

RESPONSE TO FINAL OFFICE ACTION DATED NOVEMBER 21, 2007

In response to the Final Office Action dated November 21, 2007 having a shortened statutory period for response set to expire on February 21, 2008, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although the Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782 for any other fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

*N.L.H.
2-23-08
AWE, I
entered per
RCE dated
2-21-08*